



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

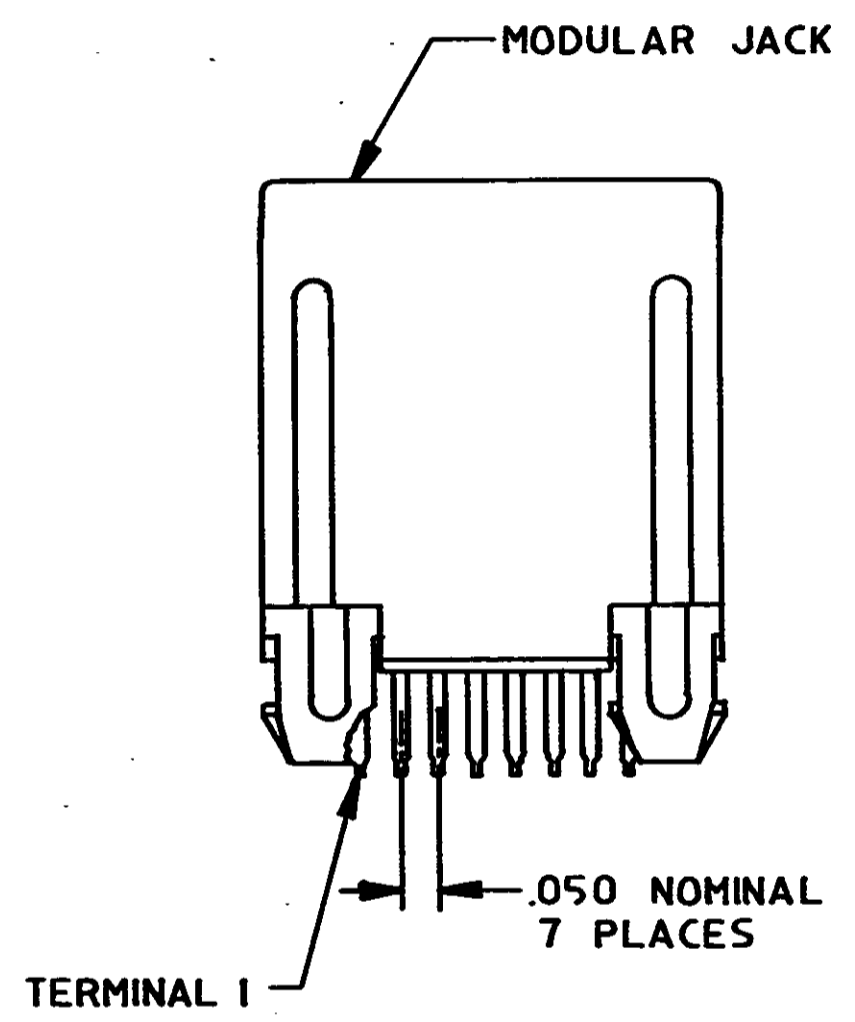
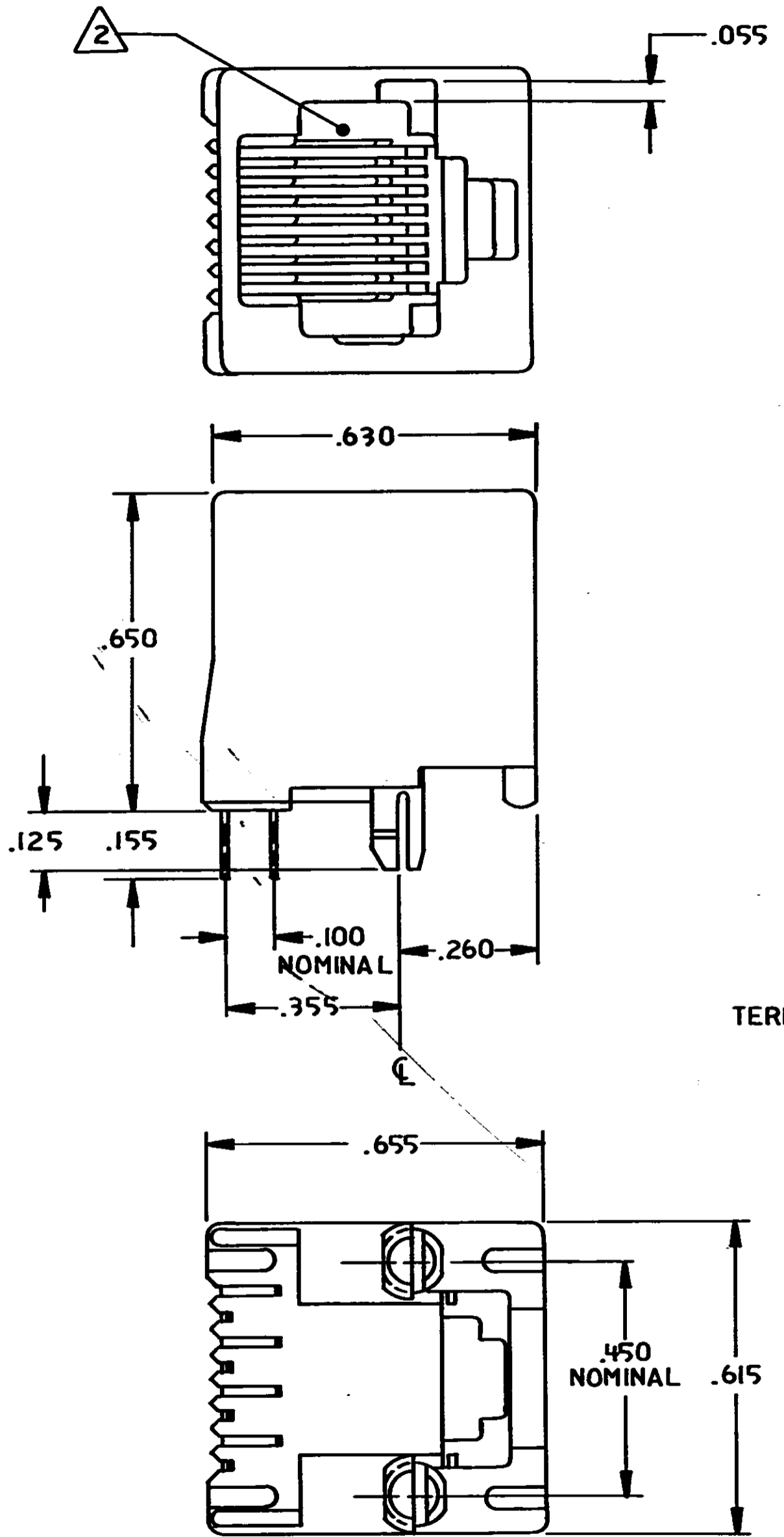
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC	DIST	REVISIONS						
AA	22	P	F	ZONE	LTR	DESCRIPTION	DATE	APPD
						C REV: ECN 0210-10-93	3-22-93	DS



- 1 MATERIAL: HOUSING—PBT POLYESTER, BLACK. TERMINAL—.0138 THICK PHOS BRONZE PLATED WITH .000050 THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND .000080 THICK TIN-LEAD IN SOLDER AREA OVER .000050 THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FFC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3. FOR APPLICATION INFORMATION SEE AMP SPECIFICATION 114-2048.
- 4. FOR PERFORMANCE REQUIREMENTS SEE AMP SPECIFICATION 108-1163.
- 5. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.

555799-1  
PART NO

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON		DR <i>DM WADDELL</i> 6-8-88		AMP   AMP INCORPORATED Harrisburg, Pa. 17105	
2 PL DEC ±	—	CHK <i>AL Clark</i> 6-13-88	NAME PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, KEYED, FLANGELESS W/O PANEL STOPS		
3 PL DEC ±	—	APPD <i>Gene Reed</i> 6-14-88	SIZE	FSCM NO	DRAWING NO
ANGLES ±	—	APPD <i>DB L...</i> 6-14-88	C	00779	555799
MATERIAL	1	PRODUCT SPEC	APPLICATION SPEC	SCALE 4:1	SHEET 1 OF 1
FINISH	1	WEIGHT			